

ALTERNATIVES TO IPA (ISOPROPYL ALCOHOL)

WHEN YOU NEED SAFER, MORE EFFECTIVE SOLUTIONS,
CALL KYZEN FOR ALTERNATIVES.

FLUX RESIDUES IN:

KYZEN Chemistry



ISOPROPYL ALCOHOL



KYZEN ADVANTAGES:

- ✓ Higher, or no flashpoint makes KYZEN products much safer than IPA when used in water-free, semi-aqueous and aqueous processes.
- ✓ KYZEN's non-ozone depleting products have much lower emissions than IPA.
- ✓ There are low, or no risk to the health and safety of the users when KYZEN products are used as recommended.



**LESS CHEMISTRY
LESS WASTE
LESS ENERGY**

IPA DISADVANTAGES:

- ✗ Highly volatile, with a great impact on emissions make it difficult to meet environmental regulations and laws.
- ✗ Low flashpoint, which creates a higher risk of fire and/or explosion.
- ✗ Consumption is much higher, which in turn can make the process cost higher.

KYZEN ALTERNATIVES TO IPA CAN BE USED IN THE FOLLOWING PROCESSES:

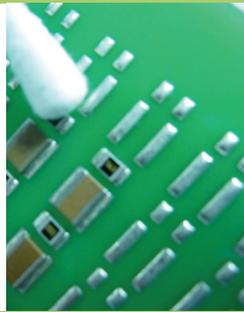
RE-WORK / BENCH-TOP CLEANING

CYBERSOLV 141-R (Precision Solvent Bench-Top Cleaner)

A precision cleaner blend of organic solvents that is effective on a wide variety of soils typically found in electronic assembly and maintenance cleaning applications.

CYBERSOLV C8882 (Bench-Top Flux Remover)

A fast-acting cleaning solvent designed to easily dissolve all flux types within the solder paste, including rosin and low residue no-clean fluxes.



MAINTENANCE & PALLET CLEANING

CYBERSOLV C8502 (Wave Solder Finger Cleaner)

Specially formulated to quickly remove all types of flux residues, C8502 is also effective on rosin flux used on fabrication of dissimilar metals on industrial components.

KYZEN E5322 (Immersion Pallet and Maintenance Cleaner)

Removes even the most difficult fluxes and solder pastes while remaining compatible with most metals and materials that require maintenance, including aluminum, copper and steel.

KYZEN E5325 (Spray-In-Air Pallet and Maintenance Cleaner)

Engineered to reduce maintenance and machine down time, while increasing production and reducing overall cost all while removing even the most baked on fluxes and solder pastes.



MANUAL STENCIL CLEANING & UNDERSTENCIL WIPE

CYBERSOLV C8882 (Understencil Wipe Stencil Cleaning Solvent)

A fast-acting cleaning solvent designed to instantly dissolve all flux types within the solder paste, including rosin and low residue no-clean fluxes.

KYZEN E5631J (Ready To Use Understencil Wipe Chemistry)

A cost-effective, ready-to-use solution for removing raw solder paste from stencils in both online and offline stencil cleaning processes, formulated with the worker and environment in mind.



OFF-LINE AUTOMATED STENCIL CLEANING

CYBERSOLV C8882 (Solvent/IPA Stencil Cleaners)

A fast-acting cleaning solvent designed to instantly dissolve all flux types within the solder paste, including rosin and low residue no-clean fluxes.

KYZEN E5631 (Ultrasonic/Spray-in-Air Cleaner)

A cost-effective solution formulated to clean flux and uncured adhesives from stencils and misprints and has proven compatible with stencils and materials of construction found in stencil cleaning equipment.

